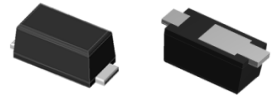


Features

- Super Low VF Schottky barrier diodes
- Low profile, typical thickness 0.8mm
- Low forward voltage drop
- Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- Heatsink structure
- High temperature soldering guaranteed: 260°C/10 seconds



Package: iSGA
(SOD-123HS)



Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Parameter	Symbol	GP17	GP18	GP19	GP1100	Unit
Maximum repetitive peak reverse voltage	V _{RRM}	70	80	90	100	V
Maximum RMS voltage	V _{RMS}	49	56	63	70	V
Maximum DC blocking voltage	V _{DC}	70	80	90	100	V
Maximum average forward rectified current	I _{F(AV)}	1.0				A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	30				A
Rating for fusing(t<8.3ms)	I ² t	3.8				A ² sec
Operating junction temperature range	T _J	- 55 to + 150				°C
Storage temperature range	T _{STG}	- 55 to + 150				°C

Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	Value	Unit
Minimum breakdown voltage	T _A =25°C, I _R =1mA	V _{BR}	100	V
Maximum instantaneous forward voltage	I _F =1A T _A =25°C	V _F	0.80	
	I _F =1A T _A =125°C		0.65	
Maximum DC reverse current at rated DC blocking voltage	T _A =25°C	I _R	1.0	uA
	T _A =125°C		150	
Typical junction capacitance	4.0 V, 1 MHz	C _J	28	pF
Typical thermal resistance	junction to ambient	R _{θJA} ¹⁾	65	°C/W
	junction to lead	R _{θJL} ¹⁾	9	
	junction to case	R _{θJC} ²⁾	35	

Note: 1), The thermal resistance from junction to ambient or lead, mounted on P.C.B with 5×5mm copper pads, 2 OZ, FR4 PCB

2), The thermal resistance from junction to case, mounted on P.C.B with recommended copper pads, 2 OZ, FR4 PCB

Typical Electrical Characteristic Curves

($T_A = 25^\circ\text{C}$ unless otherwise noted)

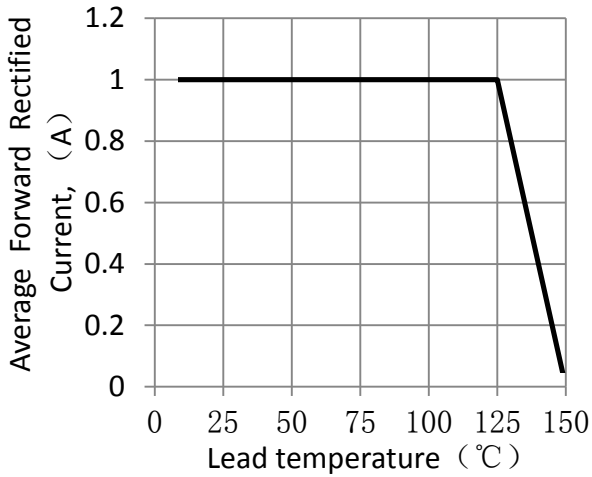


Figure 1. Forward Current Derating Curve

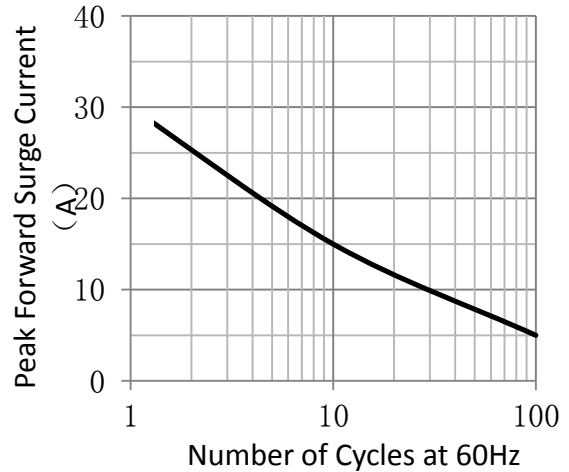


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

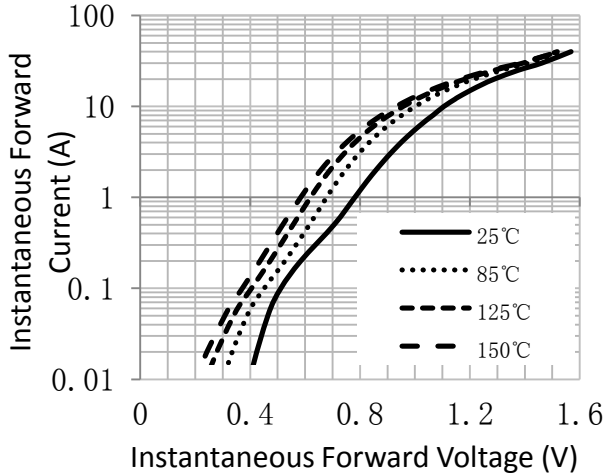


Figure 3. Typical Instantaneous Forward Characteristics

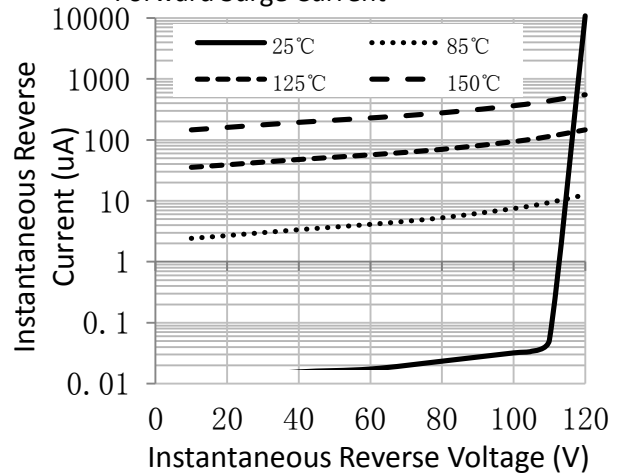


Figure 4. Typical Reverse Characteristics

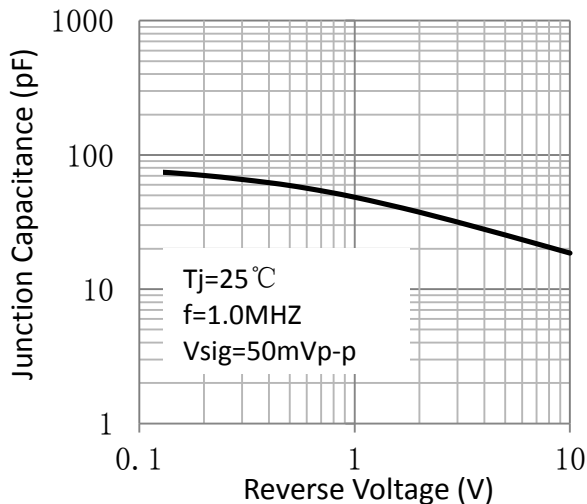


Figure 5. Typical Junction Capacitance

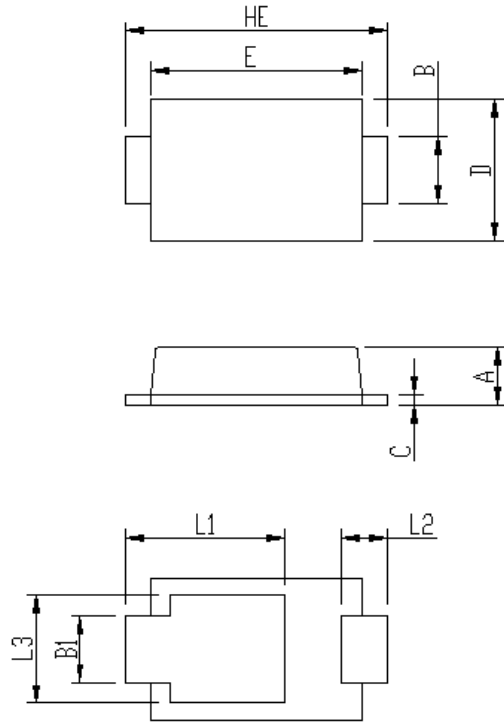
GP17 thru GP1100

Surface Mount Schottky Rectifier

Reverse Voltage 70-100V Forward Current 1.0A

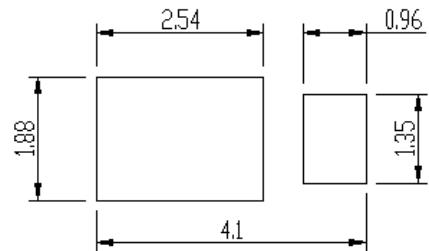
Package Outline Dimensions

iSGA
(SOD-123HS)



Package	iSGA	
Unit:mm	MIN	MAX
A	0.75	0.90
B	0.85	1.05
B1	0.85	1.05
C	0.1	0.25
D	1.9	2.1
E	2.9	3.1
L1	2.0	2.45
L2	0.4	0.85
L3	1.3	1.7
HE	3.5	3.9

Soldering footprint



Packing Information

Packing Quantities

Reel size	Quantity/reel	Quantity/inner Box	Quantity/Carton
7"	3K	30K	120K

Tape & Reel Specification

